L Number	Hits	Search Text	DB	Time stamp
1	2915	wafer adj alignment	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/23 12:14
8	110226	light same measurement	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DEPWENT;	2003/06/23
22	0	mems and ((wafer adj alignment) and (light same measurement))	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/23 12:15
15	438	(wafer adj alignment) and (light same measurement)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/23 12:16
-	16291	dicing	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/23 12:14
-	49	(wafer adj bonding and (mems or micro adj electro adj mechanical)) and dicing	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/12 10:58
_	299	wafer adj bonding and mems	DERWENT; IBM_TDB USFAT; US-PGPUB; EPO; JPO;	2003/06/12
_	46	dicing and (wafer adj bonding and mems)	DEPWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/12
-	3	("6452238").PN.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/12
_	5	("4873871" "6310371" "6326682" "6180989" "6369931").PN. 6452238.URPN.	DERWENT; IBM_TDB USPAT USPAT	2003/06/12 11:16 2003/06/12
-	972	wafer adj orientation	USPAT; US-PGPUB; EPO; JPO;	11:17 2003/06/12 11:17
-	24138	mems	DEPWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/23
_	7	(wafer adj orientation) and mems	DEPWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/12
-	327	wafer adj bonding and (mems or micro adj electro adj mechanical)	DEPWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/12 11:20
			DEPWENT; IBM TDB	

-	2475	wafer adj bonding	USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	11:21
			DERWENT;	
			IBM_TDB	
-	299	mems and (wafer adj bonding)	USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	11:21
			DERWENT;	
			IBM TDB	
-	259	dicing and (wafer adj bonding)	USPAT;	2003/06/12
			US-PGPUB;	11:21
			EPO; JPO; DERWENT;	
			IBM TDB	
_	46	mems and (dicing and (wafer adj	USPAT;	2003/06/12
		bonding))	US-PGPUB;	11:23
			EPO; JPO;	
			DERWENT; IBM TDB	
-	275443	packaging	USPAT;	2003/06/12
			US-PGPUB;	11:23
			EPO; JPO;	
1	1		DERWENT;	
_	3187	 mems and packaging	IBM_TDB USPAT;	2003/06/12
1			US-PGPUB;	11:23
			EPO; JPO;	
			DERWENT;	
	137	 dicing and (mems and packaging)	IBM_TDB USPAT;	2003/06/12
-	13/	dicing and thems and packaging)	US-PGPUB;	11:23
			EPO; JPO;	
			DERWENT;	
		(UCE 21477U\ DN	IBM_TDB	2002/05/12
-	2	("6521477").PN.	USPAT; US-PGPUB;	2003/06/12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/05/22
-	46	mems and die and second adj wafer	USPAT; US-PGPUB;	2003/06/12
			EPO; JPO;	16.67
			DEPWENT;	
			IBM_TDB	
-	12	mems adj die and holder	USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	12:27
			DERWENT;	
			IBM_TDB	
-	16		USPAT;	2003/06/12
		adj substrate	US-PGPUB; EPO; JPO;	17:18
1			DERWENT;	
			IBM_TDB	
_	76	mems and dicing and aligning	USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	17:18
			DERWENT;	
	1		IBM TDB	
_	0	1	USPĀT;	2003/06/14
		holder and dicing	US-PGPUB;	05:31
			EPO; JPO; DEPWENT;	
			IBM TDB	
_	0	cantiliever adj beam and dicing	USPAT;	2003/06/14
		-	US-PGPUB;	05:31
			EPO; JPO;	
			DEPWENT; IBM TDB	
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-	112	cantilever adj beam and dicing	USPAT;	2003/06/14
1			US-PGPUB;	05:38
	1		EPO; JPO;	
	-		DERWENT;	
			IBM TDB	
-	67	mems adj die	USPAT;	2003/06/14
	1	_	US-PGPUB;	05:38
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	4	5494698.URPN.	USPĀT	2003/06/14
				05:50